

H0947

APPLICATION DATA SHEET

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Application Information: Title: METHOD AND APPARATUS FOR PACKAGING TEST
INTEGRATED CIRCUITS
Classification: Class: Subclass:
Tech Center:
Drawing Sheets: 7 Drawing to be Published:
Docket No: H0947
Type: Utility
Secrecy: None

Representative Information: Kelly K. Kordzik, Reg. No. 36,571
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Domestic Priority:

Application:	Continuity Type:	Parent Application:	Parent Filing Date:
None			

Foreign Priority Information

Country:	Application Number:	Filing Date:	Priority Claimed:
None			

Assignee: Advanced Micro Devices, Inc.
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